2SB0642 (2SB642)

Silicon PNP epitaxial planar type

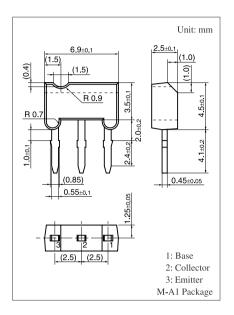
For low-power general amplification

■ Features

- High forward current transfer ratio h_{FE}
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|----------------|-------------|------|
| Collector-base voltage (Emitter open) | V_{CBO} | - 60 | V |
| Collector-emitter voltage (Base open) | V_{CEO} | - 50 | V |
| Emitter-base voltage (Collector open) | V_{EBO} | - 7 | V |
| Collector current | I_{C} | -100 | mA |
| Peak collector current | I_{CP} | -200 | mA |
| Collector power dissipation | P _C | 400 | mW |
| Junction temperature | T_j | 150 | °C |
| Storage temperature | T_{stg} | -55 to +150 | °C |



\blacksquare Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

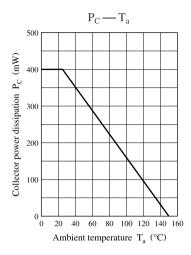
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--|----------------------|---|-------------|-----|-----|------|
| Collector-base voltage (Emitter open) | V_{CBO} | $I_{\rm C} = -10 \; \mu A, \; I_{\rm E} = 0$ | - 60 | | | V |
| Collector-emitter voltage (Base open) | V_{CEO} | $I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$ | -50 | | | V |
| Emitter-base voltage (Collector open) | V_{EBO} | $I_E = -10 \mu A, I_C = 0$ | - 7 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = -20 \text{ V}, I_E = 0$ | | | -1 | μΑ |
| Collector-emitter cutoff current (Base open) | I_{CEO} | $V_{CE} = -20 \text{ V}, I_{B} = 0$ | | | -1 | μΑ |
| Forward current transfer ratio * | h_{FE} | $V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$ | 160 | | 460 | _ |
| Collector-emitter saturation voltage | V _{CE(sat)} | $I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$ | | | -1 | V |
| Transition frequency | f_T | $V_{CB} = -10 \text{ V}, I_E = 2 \text{ mA}, f = 200 \text{ MHz}$ | | 80 | | MHz |
| Collector output capacitance | C _{ob} | $V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 3.5 | | pF |
| (Common-emitter reverse transfer) | | | | | | |

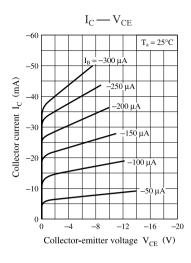
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

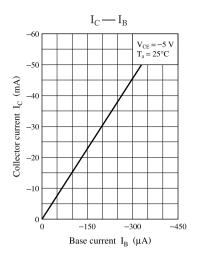
2. *: Rank classification

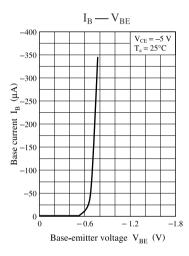
| Rank | Q | R | S |
|---------------|------------|------------|------------|
| $h_{\rm FE1}$ | 160 to 260 | 210 to 340 | 290 to 460 |

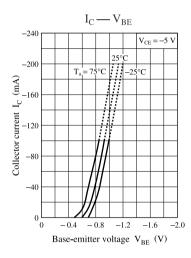
Note) The part number in the parenthesis shows conventional part number.

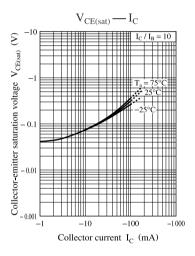


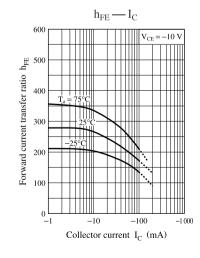


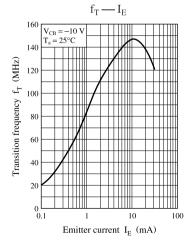


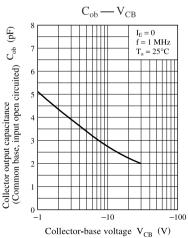


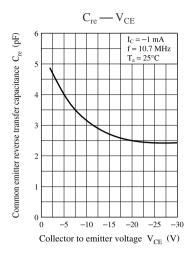


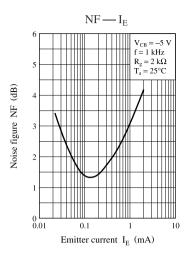


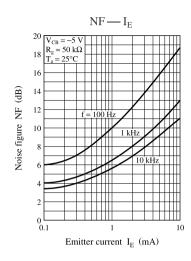


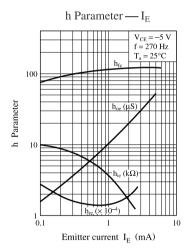


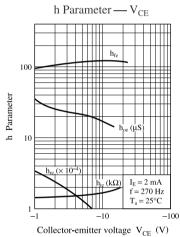


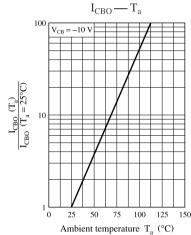












SJC00045BED 3

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